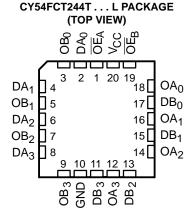
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- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- CY54FCT244T
 - 48-mA Output Sink Current
 12-mA Output Source Current
- CY74FCT244T
 - 64-mA Output Sink Current
 32-mA Output Source Current
- 3-State Outputs

CY54FCT244T...D PACKAGE CY74FCT244T . . . P, Q, OR SO PACKAGE (TOP VIEW) OE_A [19 TOEB $DA_0 \prod 2$ ОВ₀ 🛛 з 18**∏** OA₀ DA₁ [] 4 DΒ₀ 17 OB₁ **[**] 5 16 OA₁ $DA_2 \begin{bmatrix} 1 \\ 6 \end{bmatrix}$ 15 DB₁ OB₂ [] 7 14 DA₃ [] 8 DB₂ 13 12 OA₃ OB₃ [] 9 11 DB₃ GND [] 10



description

The 'FCT244T devices are octal buffers and line drivers designed to be employed as memory address drivers, clock drivers, and bus-oriented transmitters/receivers. These devices provide speed and drive capabilities equivalent to their fastest bipolar logic counterparts, while reducing power consumption. The input and output voltage levels allow direct interface with TTL, NMOS, and CMOS devices without external components.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



CY54FCT244T, CY74FCT244T 8-BIT BUFFERS/LINE DRIVERS WITH 3-STATE OUTPUTS SCCS071 – OCTOBER 2001

ORDERING INFORMATION

TA	PACI	KAGE†	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE Marking
	QSOP - Q	Tape and reel	3.6	CY74FCT244DTQCT	FCT244D
0°C to 70°C	SOIC - SO	Tube	3.6	CY74FCT244DTSOC	FCT244D
	30IC - 30	Tape and reel	3.6	CY74FCT244DTSOCT	FC1244D
	SOIC – SO Tube		4.1	CY74FCT244CTSOC	FCT244C
	3010 - 30	Tape and reel	4.1	CY74FCT244CTSOCT	FC1244C
	QSOP - Q	Tape and reel	4.1	CY74FCT244CTQCT	FCT244C
	DIP – P	Tube	4.6	CY74FCT244ATPC	CY74FCT244ATPC
–40°C to 85°C	SOIC - SO	Tube	4.6	CY74FCT244ATSOC	FCT244A
-40°C 10 65°C	30IC - 30	Tape and reel	4.6	CY74FCT244ATSOCT	FC1244A
	QSOP - Q	Tape and reel	4.6	CY74FCT244ATQCT	FCT244A
	SOIC - SO	Tube	6.5	CY74FCT244TSOC	FCT244
	30IC - 30	Tape and reel	6.5	CY74FCT244TSOCT	FC1244
	QSOP - Q	Tape and reel	6.5	CY74FCT244TQCT	FCT244
	CDIP – D	Tube	4.6	CY54FCT244CTDMB	
	LCC – L	Tube	4.6	CY54FCT244CTLMB	
EE0C to 10E0C	CDIP – D	Tube	5.1	CY54FCT244ATDMB	
_	LCC – L	Tube	5.1	CY54FCT244ATLMB	
	CDIP – D	Tube	7	CY54FCT244TDMB	
	LCC – L	Tube	7	CY54FCT244TLMB	

 $^{^{\}dagger} \, \text{Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available}$ at www.ti.com/sc/package.

FUNCTION TABLE

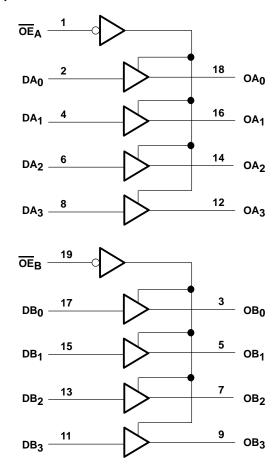
	INPUTS	OUTPUT	
ŌĒĄ	OE B	D	0
L	L	L	L
L	L	Н	Н
Н	Н	Χ	Z

H = High logic level, L = Low logic level, X = Don't care, Z = High-impedance state



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logic diagram (positive logic)



absolute maximum rating over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential	–0.5 V to 7 V
DC input voltage range	–0.5 V to 7 V
DC output voltage range	–0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ _{JA} (see Note 1): P package	69°C/W
Q package	68°C/W
SO package	58°C/W
Ambient temperature range with power applied, T _A	−65°C to 135°C
Storage temperature range, T _{stq}	−65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



CY54FCT244T, CY74FCT244T 8-BIT BUFFERS/LINE DRIVERS WITH 3-STATE OUTPUTS SCCS071 - OCTOBER 2001

recommended operating conditions (see Note 2)

		CY	54FCT24	4T	CY7	4FCT24	1DT	CY	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	4.75	5	5.25	V
VIH	High-level input voltage	2			2			2			V
V_{IL}	Low-level input voltage			0.8			0.8			0.8	V
ІОН	High-level output current			-12			-32			-32	mA
loL	Low-level output current			48			64			64	mA
TA	Operating free-air temperature	-55		125	0		70	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

242445752		TEST SOUDITION		CY	54FCT24	I4T	CY	74FCT24	4T	
PARAMETER		TEST CONDITION	V 5	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
V	$V_{CC} = 4.5 \text{ V},$	$I_{IN} = -18 \text{ mA}$			-0.7	-1.2				V
VIK	$V_{CC} = 4.75 \text{ V},$	$I_{IN} = -18 \text{ mA}$						-0.7	-1.2	V
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -12 \text{ mA}$		2.4	3.3					
Voн	V _{CC} = 4.75 V	$I_{OH} = -32 \text{ mA}$					2			V
	VCC = 4.75 V	$I_{OH} = -15 \text{ mA}$					2.4	3.3		
Va	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 48 \text{ mA}$			0.3	0.55				٧
VOL	$V_{CC} = 4.75 \text{ V},$	$I_{OL} = 64 \text{ mA}$						0.3	0.55	V
V_{hys}	All inputs				0.2			0.2		>
1.	$V_{CC} = 5.5 \text{ V},$	VIN = VCC				5				μΑ
-	$V_{CC} = 5.25 \text{ V},$	VIN = VCC							5	μΑ
1	$V_{CC} = 5.5 \text{ V},$	$V_{1N} = 2.7 \text{ V}$				±1				μΑ
ЧH	$V_{CC} = 5.25 \text{ V},$	$V_{1N} = 2.7 \text{ V}$							±1	μΑ
1	$V_{CC} = 5.5 \text{ V},$	$V_{1N} = 0.5 V$				±1				μА
<u>ا</u> ا	$V_{CC} = 5.25 \text{ V},$	$V_{1N} = 0.5 V$							±1	μΑ
10711	$V_{CC} = 5.5 \text{ V},$	V _{OUT} = 2.7 V				10				μА
IOZH	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 2.7 V							10	μΑ
lo-	$V_{CC} = 5.5 \text{ V},$	V _{OUT} = 0.5 V				-10				μА
lozL	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 0.5 V							-10	μΑ
los‡	$V_{CC} = 5.5 \text{ V},$	V _{OUT} = 0 V		-60	-120	-225				mA
iOS+	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 0 V					-60	-120	-225	ША
l _{off}	$V_{CC} = 0 V$	V _{OUT} = 4.5 V				±1			±1	μΑ
laa	$V_{CC} = 5.5 V$,	$V_{IN} \le 0.2 V$,	$V_{IN} \ge V_{CC} - 0.2 V$		0.1	0.2				mA
Icc	$V_{CC} = 5.25 \text{ V},$	$V_{IN} \le 0.2 V$	$V_{IN} \ge V_{CC} - 0.2 V$					0.1	0.2	IIIA
Alaa	V _{CC} = 5.5 V, V _{IN} =	: 3.4 V [§] , f ₁ = 0, Out	puts open		0.5	2				mA
∆ICC	$V_{CC} = 5.25 \text{ V}, V_{IN}$	$= 3.4 \text{ V}$, $f_1 = 0$, Ou	itputs open					0.5	2	IIIA
	$V_{CC} = 5.5 \text{ V}, O_{ne} \text{ i}$	nput switching at 50	0% duty cycle,		2.22	0.40				
_	Outputs open, OE _A V _{IN} ≤ 0.2 V or V _{IN}	$\lambda = OEB = GND$, $\geq VCC = 0.2 V$			0.06	0.12				mA/
ICCD¶		input switching at 5	50% duty cycle.							MHz
	Outputs open, OE	$\chi = \overline{OE}_B = GND$,	22.2 20.9 0,0.0,					0.06	0.12	
	$V_{IN} \le 0.2 \text{ V or } V_{IN}$	≥ V _{CC} – 0.2 V								

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, Ios tests should be performed last.

[§] Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND

This parameter is derived for use in total power-supply calculations.

CY54FCT244T, CY74FCT244T 8-BIT BUFFERS/LINE DRIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

DADAMETER		TEST CONDITIONS	,	CY	54FCT24	14T	CY	74FCT24	4T	LINUT
PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
		One bit switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4				
	$V_{CC} = 5.5 \text{ V},$	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		1	2.4				
	Outputs open, OE _A = OE _B = GND	Eight bits switching	$V_{IN} = 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		1.3	2.6				
IC#		at f ₁ = 2.5 MHz at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		3.3	10.6				mA
IC"		One bit switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	1.4	IIIA
	$V_{CC} = 5.25 \text{ V},$	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$					1	2.4	
	Outputs open, OE _A = OE _B = GND	Eight bits switching at f ₁ = 2.5 MHz	$V_{IN} = 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					1.3	2.6	
		at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$					3.3	10.6	
Ci					5	10		5	10	pF
Co					9	12		9	12	pF

 $[\]overline{\dagger}$ Typical values are at V_{CC} = 5 V, T_A = 25°C.

 $^{\#}$ IC = ICC + Δ ICC \times DH \times NT + ICCD (f₀/2 + f₁ \times N₁)

Where:

IC = Total supply current

ICC = Power-supply current with CMOS input levels

 ΔI_{CC} = Power-supply current for a TTL high input (V_{IN} = 3.4 V)

 D_H = Duty cycle for TTL inputs high N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

f₀ = Clock frequency for registered devices, otherwise zero

f₁ = Input signal frequency

N₁ = Number of inputs changing at f₁

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.



CY54FCT244T, CY74FCT244T 8-BIT BUFFERS/LINE DRIVERS WITH 3-STATE OUTPUTS SCCS071 - OCTOBER 2001

switching characteristics over operating free-air temperature range (see Figure 1)

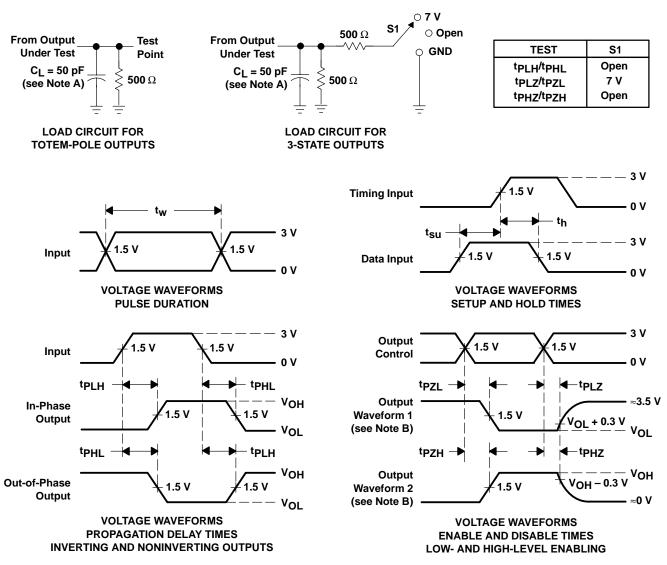
PARAMETER	FROM	то	CY54FC	CY54FCT244T		CY54FCT244AT		CY54FCT244CT		
PARAWETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNIT	
^t PLH	D	0	1.5	7	1.5	5.1	1.5	4.6	ns	
^t PHL	D	0	1.5	7	1.5	5.1	1.5	4.6	110	
^t PZH	ŌĒ	0	1.5	8.5	1.5	6.5	1.5	6.5	20	
t _{PZL}	OE	O	1.5	8.5	1.5	6.5	1.5	6.5	ns	
^t PHZ	ŌĒ	0	1.5	7.5	1.5	5.9	1.5	5.7	20	
^t PLZ	OE	U	1.5	7.5	1.5	5.9	1.5	5.7	ns	

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY74FCT244T		CY74FCT244AT		CY74FCT	244CT	CY74FCT	244DT	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	CIVIT	
tPLH	D	0	1.5	6.5	1.5	4.6	1.5	4.1	1.5	3.6	20	
t _{PHL}	D	0	1.5	6.5	1.5	4.6	1.5	4.1	1.5	3.6	ns	
^t PZH	ŌE	0	1.5	8	1.5	6.2	1.5	5.8	1.5	4.8	ns	
t _{PZL}	OE	0	1.5	8	1.5	6.2	1.5	5.8	1.5	4.8	115	
^t PHZ	ŌE	0	1.5	7	1.5	5.6	1.5	5.2	1.5	4	ne	
^t PLZ	OE .	J	1.5	7	1.5	5.6	1.5	5.2	1.5	4	ns	

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9220301M2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9220301M2A CY54FCT 244TLMB	Samples
5962-9220301MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9220301MR A CY54FCT244TDMB	Samples
5962-9220301MSA	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9220301MS A CY54FCT244TW	Samples
5962-9220302M2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9220302M2A CY54FCT 244ATLMB	Samples
5962-9220302MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9220302MR A CY54FCT244ATDM B	Samples
5962-9220302MSA	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9220302MS A CY54FCT244ATW	Samples
5962-9220303M2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9220303M2A	Samples
5962-9220303MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9220303MR A CY54FCT244CTDM B	Samples
CY54FCT244ATDMB	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9220302MR A CY54FCT244ATDM B	Samples
CY54FCT244ATLMB	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9220302M2A CY54FCT 244ATLMB	Samples





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CY54FCT244ATW	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9220302MS A CY54FCT244ATW	Samples
CY54FCT244CTDMB	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9220303MR A CY54FCT244CTDM B	Samples
CY54FCT244TDMB	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9220301MR A CY54FCT244TDMB	Samples
CY54FCT244TLMB	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9220301M2A CY54FCT 244TLMB	Samples
CY54FCT244TW	ACTIVE	CFP	W	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9220301MS A CY54FCT244TW	Samples
CY74FCT244ATPC	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	CY74FCT244ATPC	Samples
CY74FCT244ATQCT	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT244A	Samples
CY74FCT244ATQCTE4	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT244A	Samples
CY74FCT244ATSOC	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244A	Samples
CY74FCT244ATSOCT	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244A	Samples
CY74FCT244CTQCT	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT244C	Samples
CY74FCT244CTSOC	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244C	Samples
CY74FCT244DTSOC	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244D	Samples
CY74FCT244DTSOCT	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244D	Samples
CY74FCT244TQCT	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT244	Samples
CY74FCT244TSOC	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244	Samples

PACKAGE OPTION ADDENDUM

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CY74FCT244TSOCT	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT244	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

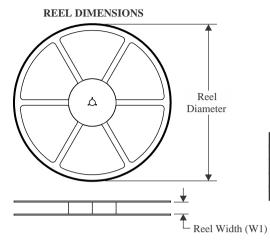
- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

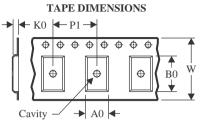
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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

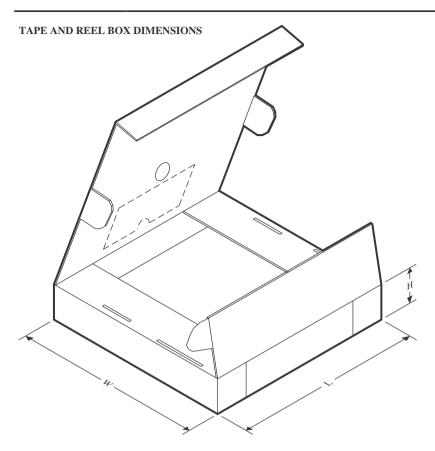


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT244ATQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT244ATSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
CY74FCT244CTQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT244DTSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
CY74FCT244TQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT244TSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1



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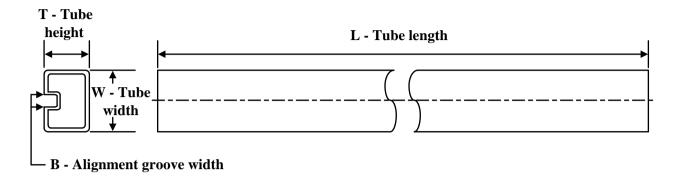
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT244ATQCT	SSOP	DBQ	20	2500	356.0	356.0	35.0
CY74FCT244ATSOCT	SOIC	DW	20	2000	367.0	367.0	45.0
CY74FCT244CTQCT	SSOP	DBQ	20	2500	356.0	356.0	35.0
CY74FCT244DTSOCT	SOIC	DW	20	2000	367.0	367.0	45.0
CY74FCT244TQCT	SSOP	DBQ	20	2500	356.0	356.0	35.0
CY74FCT244TSOCT	SOIC	DW	20	2000	367.0	367.0	45.0



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TUBE

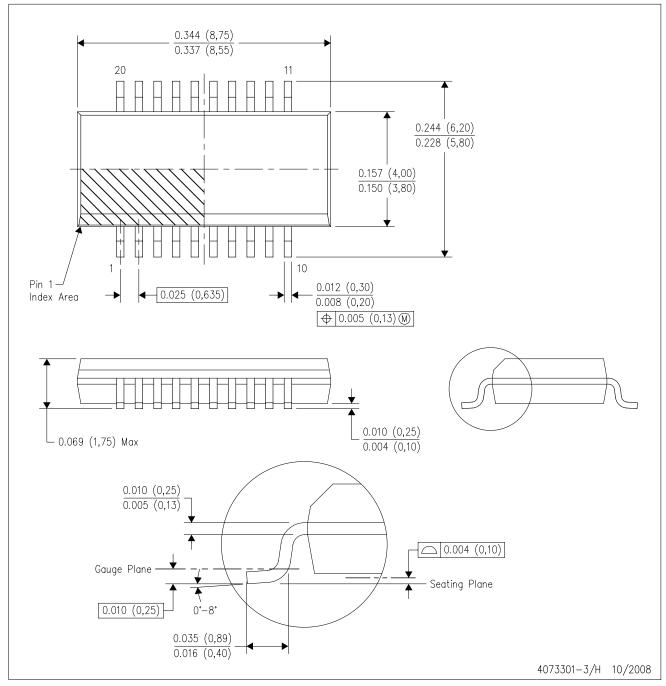


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9220301M2A	FK	LCCC	20	1	506.98	12.06	2030	NA
5962-9220301MSA	W	CFP	20	1	506.98	26.16	6220	NA
5962-9220302M2A	FK	LCCC	20	1	506.98	12.06	2030	NA
5962-9220302MSA	W	CFP	20	1	506.98	26.16	6220	NA
5962-9220303M2A	FK	LCCC	20	1	506.98	12.06	2030	NA
CY54FCT244ATLMB	FK	LCCC	20	1	506.98	12.06	2030	NA
CY54FCT244ATW	W	CFP	20	1	506.98	26.16	6220	NA
CY54FCT244TLMB	FK	LCCC	20	1	506.98	12.06	2030	NA
CY54FCT244TW	W	CFP	20	1	506.98	26.16	6220	NA
CY74FCT244ATPC	N	PDIP	20	20	506	13.97	11230	4.32
CY74FCT244ATSOC	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT244CTSOC	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT244DTSOC	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT244TSOC	DW	SOIC	20	25	507	12.83	5080	6.6

DBQ (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
- D. Falls within JEDEC MO-137 variation AD.



14 LEADS SHOWN

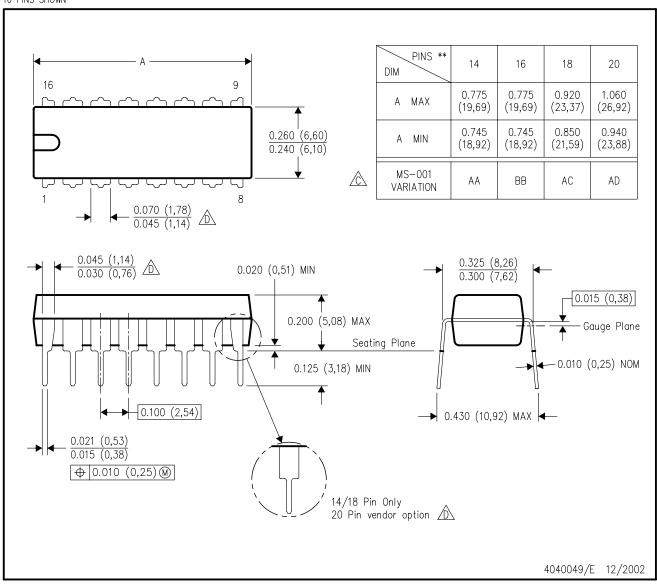


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

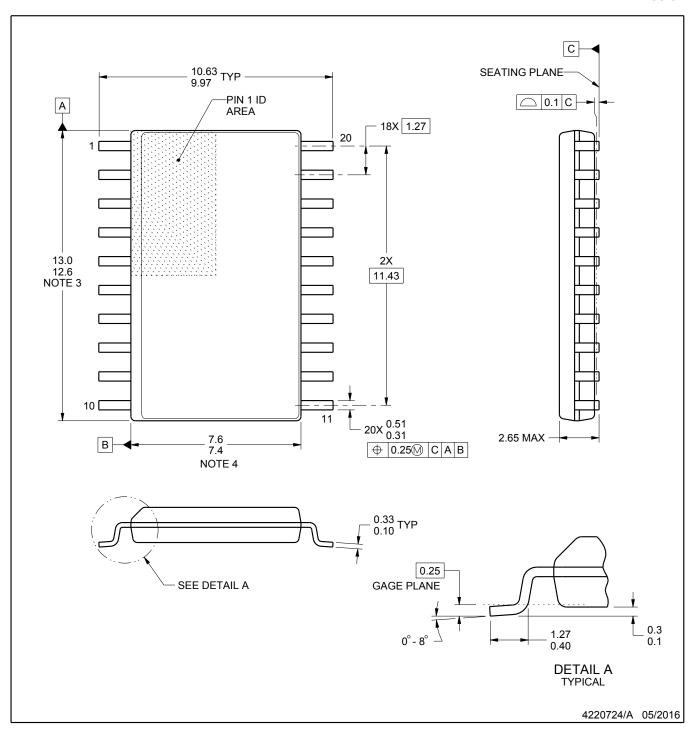


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



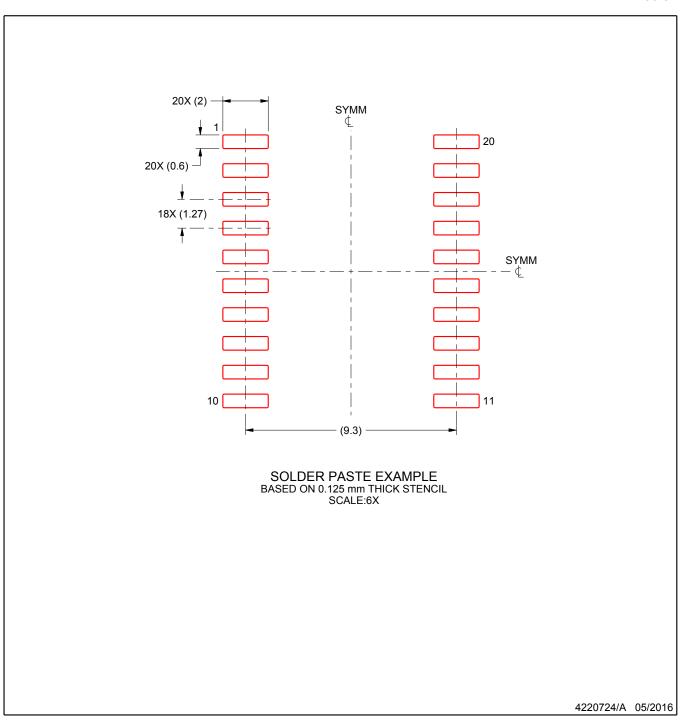
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



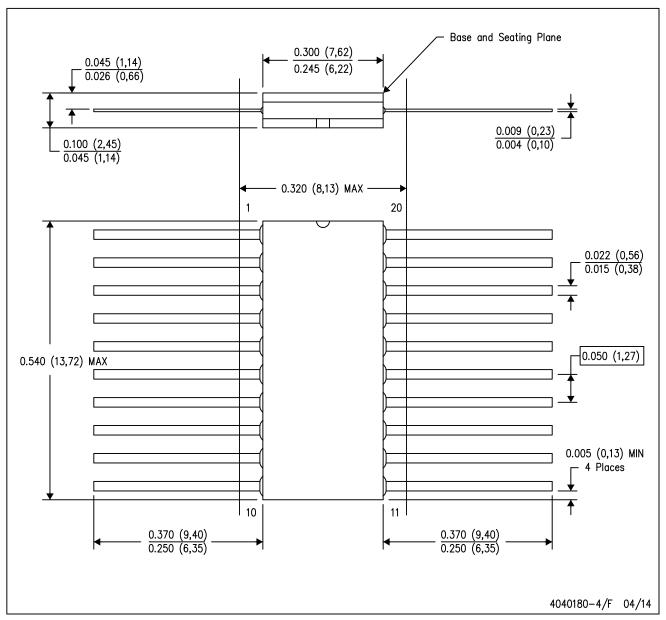
NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

 D. Index point is provided on cap for terminal identification only.

 E. Falls within Mil—Std 1835 GDFP2—F20



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